## <u>AMENDMENTS</u>

## CLAIMS:

## 1-30 (Cancelled)

- 31. (New) A method for topographical patterning, the method comprising the steps of:
- (a) positioning a mask relative to a device, the mask being in the form of a pattern, wherein the mask exposes a surface of the device;
- (b) etching the pattern into a surface of the device to form a feature, wherein said feature includes at least one rounded edge; and
- (c) providing a mating element and connecting said mating element and said feature.
- 32. (New) The method of claim 31, wherein the feature is formed into the substrate.
- 33. (New) The method of claim 32, wherein the feature is selected from at least one of a rounded shape, an oval shape, or a square shape.
- 34. (New) The method of claim 31, wherein the feature is protruding from the substrate.
- 35. (New) The method of claim 34, wherein the feature is selected from at least one of a rounded shape, an oval shape, or a square shape.
- 36. (New) The method of claim 31, wherein the rounded edge is an arcuate edge.
- 37. (New) The method of claim 31, wherein the pattern of the mask is formed with variable spacings to produce the rounded edge.
- 38. (New) The method of claim 37, wherein the variable spacings in the pattern of the mask are varied to vary the rounded shape.

- 39. (New) The method of claim 31, wherein the etching step (b) comprises immersing the device within a liquid.
- 40. (New) The method of claim 31, wherein the etching step (b) comprises spraying a liquid against the surface of the device.
- 41. (New) The method of claim 31, wherein the etching step (b) comprises exposing the surface of the device to a vapor.
- 42. (New) The method of claim 31, wherein the etching step (b) comprises exposing the surface of the device to a plasma.
- 43. (New) The method of claim 31, wherein the etching step (b) comprises directing an ion beam at the surface of the device.
- 44. (New) The method of claim 31, wherein the device comprises more than one layer and the etching step (b) comprises etching into one or more of the layers.
- 45. (New) A method for topographical patterning of a MEMS device, the method comprising the steps of:
- (a) etching a pattern into a surface of the MEMS device to form a feature, wherein said feature includes at least one rounded edge; and
- (b) providing a mating element; and
- (c) inserting the mating element into the feature, wherein the rounded edge reduces damage to the feature.
- 46. (New) The method of claim 45, wherein the feature is formed into the substrate.
- 46. (New) The method of claim 32, wherein the feature is selected from at least one of a rounded shape, an oval shape, or a square shape.

- 47. (New) The method of claim 31, wherein the feature is protruding from the substrate.
- 48. (New) The method of claim 34, wherein the feature is selected from at least one of a rounded shape, an oval shape, or a square shape.
- 49. (New) The method of claim 31, wherein the rounded edge is an arcuate edge.